

## MN34110PA Data Sheet

### Overview

This product is MOS type image sensor of Type-1/2.33" 14.24 mega pixels. R,G,B primary color mosaic filters are used as the color filters. In the still mode, the signal of 14.24 mega pixels can be output to the high-resolution ultra-high-density. The FHD movie is achieved by vertical and horizontal mixing.

### Feature

Parameter	Content	
Scan mode	Progressive scan	
Optical size	1/2.33 type 4:3 aspect	
Number of effective pixels	4,348 (H) × 3,276 (V) = 14,244,048 (pixel)	
Number of active pixels	4,320 (H) × 3,252 (V) = 14,048,640 (pixel)	
Total number of pixels	4,490 (H) × 3,412 (V) = 15,319,880 (pixel)	
Pixel size	1.43 (H) μm × 1.43 (V) μm	
Package	LGA Package (Ceramics)	
Actual imaging area dimensions (active pixel area)	6177.6 (H) μm × 4650.4 (V) μm	
Color filter arrangement	R,G,B primary color mosaic filters	
Power supply voltage	3.3V / 1.8V / 1.2V	
Master clock	Typ. 54 MHz	
Output signal type	subLVDS DDR method 594 Mbps	
Register I/F	4-wire Serial I/F	
Driving mode	Full scan1(1ch8port/12bit)	18fps : 4320H × 3252V
	Full scan2(1ch8port/10bit)	23fps : 4320H × 3252V
	1080p mode(1ch8port/12bit)	60fps : 2160H × 1216V
	720p mode(1ch4port/12bit)	60fps : 1440H × 810V
	Monitor mode(1ch2port/12bit)	30fps : 1440H × 464V

### Application

- Digital Still Camera
- Camcorder

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